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(54) **THERMOSETTING RESIN COMPOSITION FOR SEALING AND ELECTRONIC COMPONENT DEVICE**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a thermosetting resin composition for sealing which has good moldability such as a flow property or an adhesion property, good reflow crack resistance and is reliable to such as moisture resistance or a high- temperature aging characteristic and is excellent storage stability, and to provide an electronic component device equipped with

the elements sealed with it.

SOLUTION: The thermosetting resin composition for sealing contains (A) a thermosetting resin having a dihydrobenzoxazine ring, (B) an epoxy resin, (C) a phenolic resin, (D) an ion scavenger and (E) an inorganic filler. The melt viscosity of a resin composition consisting of the components (A), (B) and (C) at 150°C is 2 poise or below and the content of the component (D) is kept to 0.5-20 pts.wt. based on 100 pts.wt. of the resin component.

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